

LNJ626W8CRA

Surface Mounting Chip LED

UTSS Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	70	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	70	mA
Reverse voltage	V_R	5	V
Operating ambient temperature	T_{opr}	-30 to +85	°C
Storage temperature	T_{stg}	-40 to +100	°C

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color

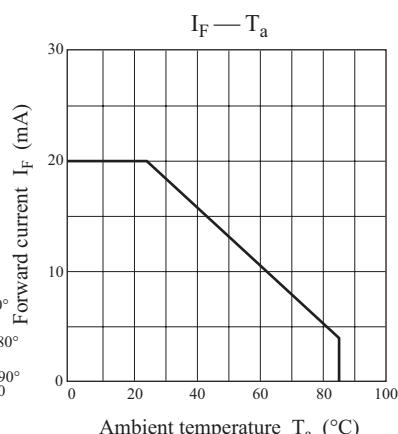
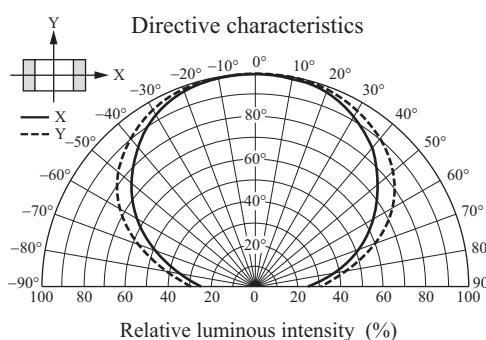
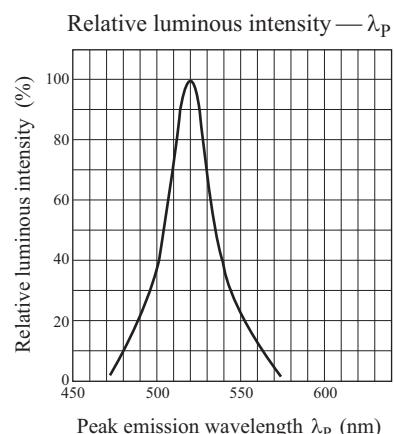
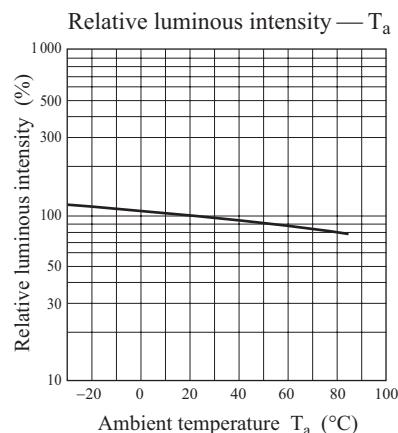
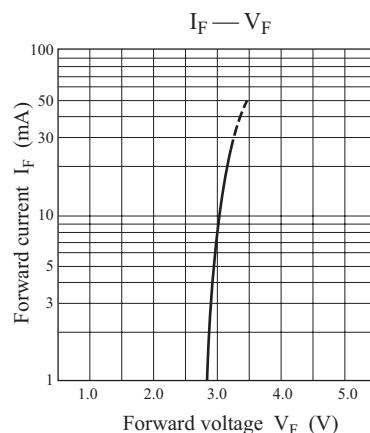
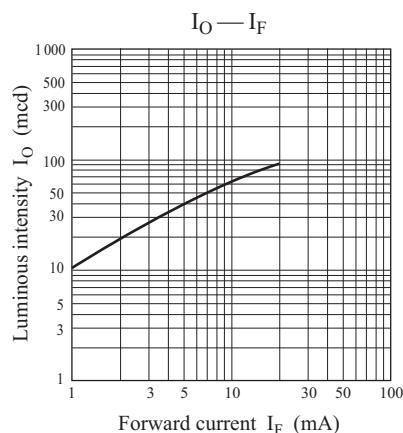
- Pure Green

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

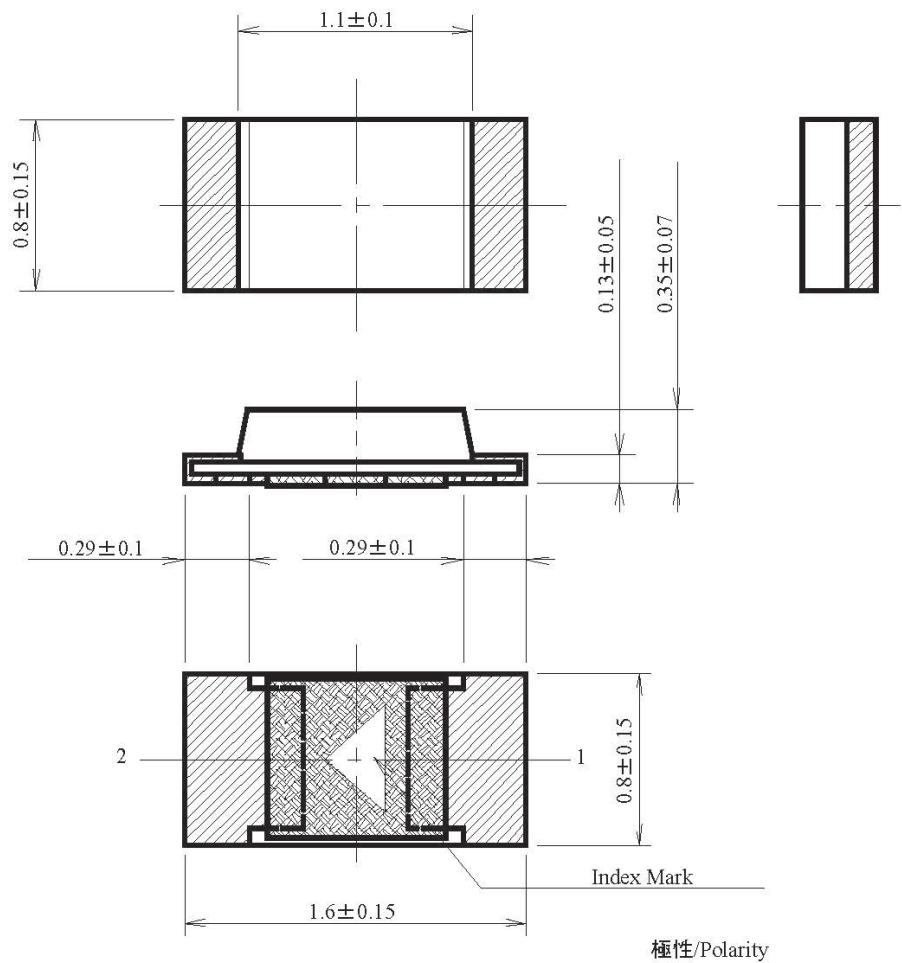
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *1	I_O	$I_F = 5 \text{ mA}$	15.0	40.0	119.0	mcd
Reverse current	I_R	$V_R = 5 \text{ V}$			100	μA
Forward voltage	V_F	$I_F = 5 \text{ mA}$	2.65	2.90	3.25	V
Peak emission wavelength	λ_P	$I_F = 5 \text{ mA}$		520		nm
Dominant emission wavelength *2	λ_d	$I_F = 5 \text{ mA}$	518	527	538	nm
Spectral half band width	$\Delta\lambda$	$I_F = 5 \text{ mA}$		30		nm

Note) *1: Measurement tolerance: $\pm 20\%$

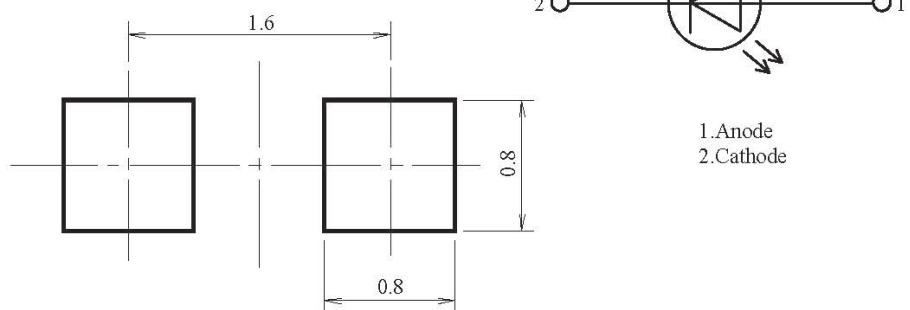
*2: Measurement tolerance: $\pm 3 \text{ nm}$



■ Package (Unit: mm)



推奨パターン
Recommended Land Layout



注記/Notes

- 1.パッケージ寸法については電極バリを含まない。
Measurement of the package doesn't include electrode projection.
- 2.単位:mm/Unit : mm

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